



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD036N04L G		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001662060						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		314.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	0.72	0.72	7152	7152
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		456	
	non noble metal	copper	7440-50-8	143.098	45.54	45.60	455468	456061
	non noble metal	aluminium	7429-90-5	3.668	1.17	1.17	11676	11676
wire	inorganic material	antimonytrioxide	1309-64-4	1.957	0.62		6230	
encapsulation	plastics	brominated resin	-	2.097	0.67		6675	
	organic material	carbon black	1333-86-4	2.237	0.71		7120	
	plastics	epoxy resin	-	18.875	6.01		60079	
	inorganic material	silicondioxide	60676-86-0	114.651	36.49	44.50	364924	445028
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11904	11904
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
solder	non noble metal	tin	7440-31-5	0.043	0.01		136	
	noble metal	silver	7440-22-4	0.053	0.02		170	
	non noble metal	lead	7439-92-1	2.035	0.65	0.68	6478	6784
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.10	6.11	61040	61119
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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